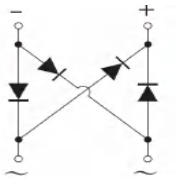
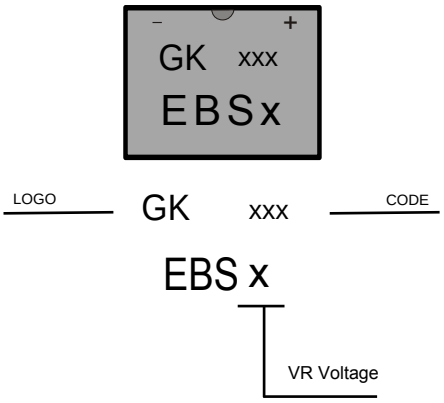
FEATURES

* Ideal for printed circuit board
* Reliable low cost construction utilizing molded plastic technique
* High surge current capability
* Polarity: Symbol molded on body
* Mounting position: Any

VOLTAGE RANGE
200 to 600 Volts
CURRENT
1.0 Ampere



Internal Schematic



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

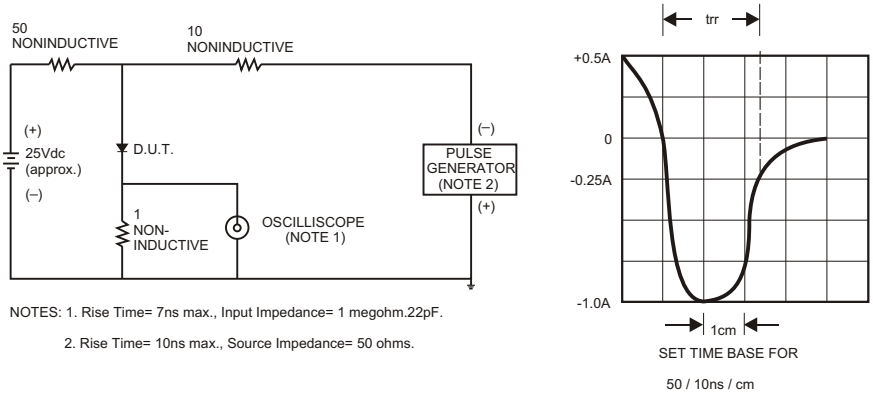
Rating 25℃ ambient temperature uniess otherwies specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	EBS2	EBS4	EBS6	UNITS
Maximum Recurrent Peak Reverse Voltage	200	400	600	V
Maximum RMS Voltage	140	280	480	V
Maximum DC Blocking Voltage	200	400	600	V
Maximum Average Forward Rectified Current	1.0			A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	30			A
Maximum Forward Voltage Drop per Bridge Element at 0.5A D.C.	1.0	1.3	1.7	V
Maximum DC Reverse Current Ta=25℃	5.0			μA
at Rated DC Blocking Voltage Ta=100℃	200			μA
Maximum Reverse Recovery Time (Note 1)	35			nS
Typical Junction Capacitance (Note 2)	15			pF
Typical Thermal Resistance R JA (Note 3)	75			℃/W
Operating and Storage Temperature Range T_J, T_{STG}	-65 — +150			℃

NOTES: 1. Reverse Recovery Time test condition: IF=0.5A, IR=1.0A, IRR=0.25A
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3. Thermal Resistance from Junction to Ambient.

RATING AND CHARACTERISTIC CURVES

FIG.1- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.

2. Rise Time= 10ns max., Source Impedance= 50 ohms.

FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

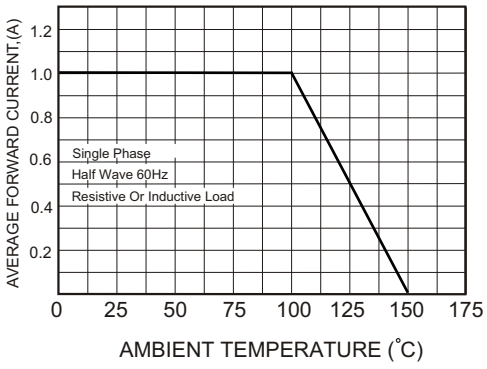


FIG.2-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

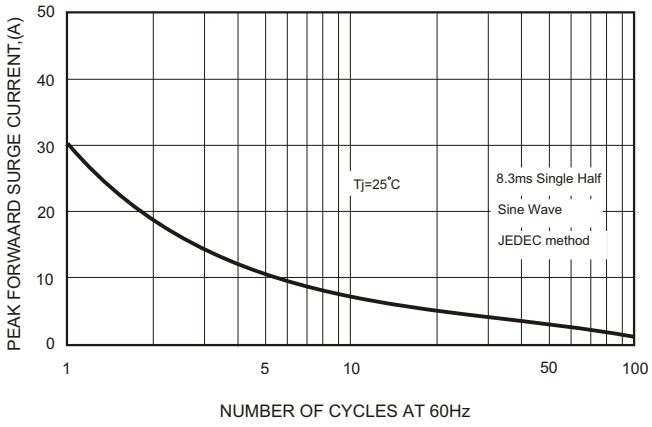


FIG.4-TYPICAL FORWARD CHARACTERISTICS

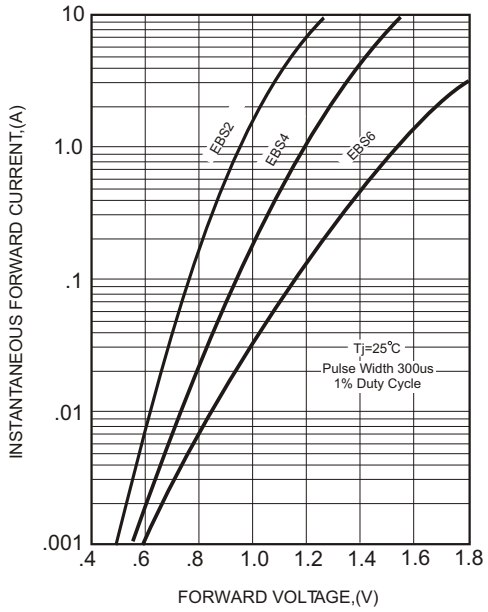
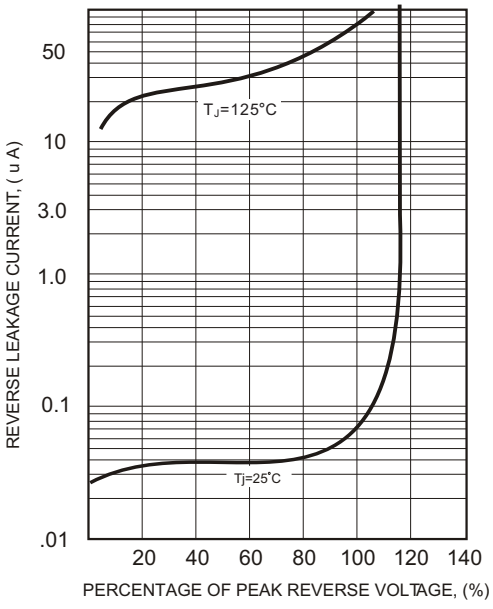


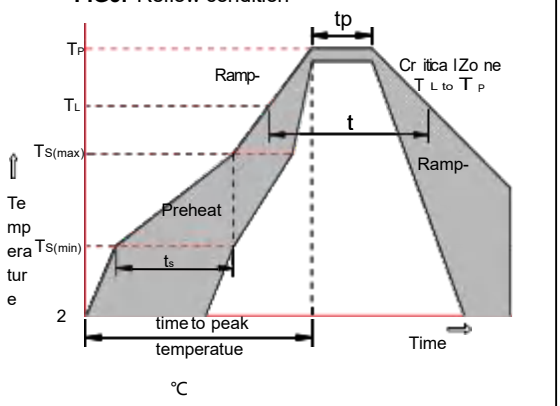
FIG.5-TYPICAL REVERSE CHARACTERISTICS



Soldering parameters

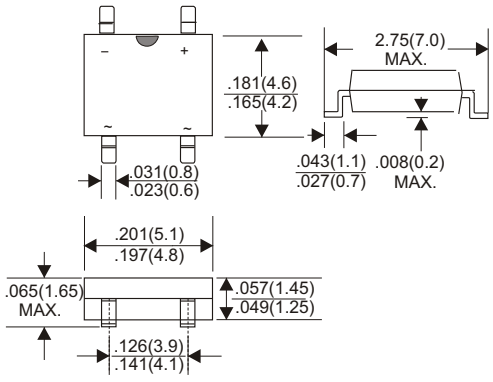
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition

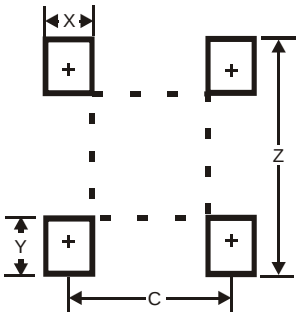


Package Dimensions & Suggested Pad Layout

ABS



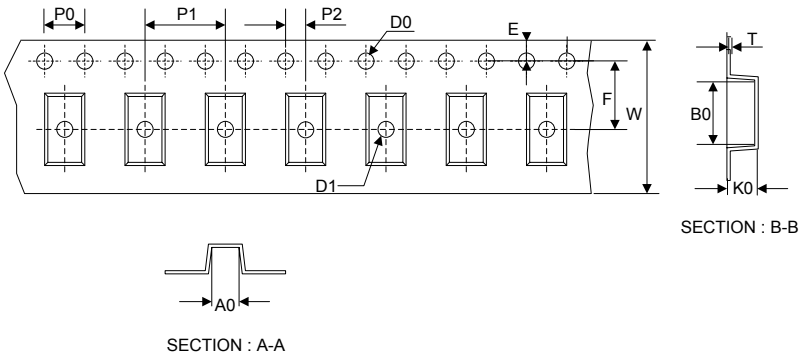
Dimensions in inches and (millimeters)



Dimensions	
Z	8.4
X	1.0
Y	2.2
C	4.0

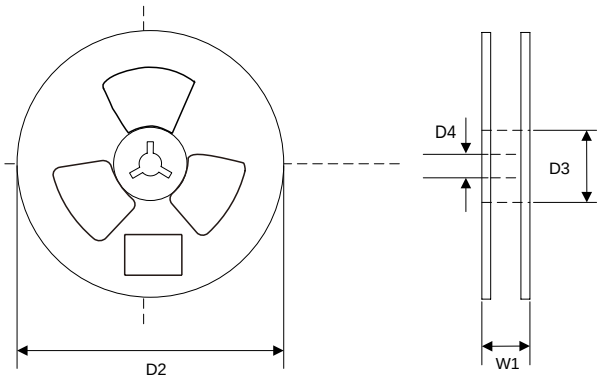
Tape & rell specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.20
P1	8.00±0.20
P2	2.00±0.20
D0	1.60±0.15
D1	1.60±0.15
E	1.75±0.20
F	5.50±0.15
W	12.00±0.20
A0	5.30±0.20
B0	6.80±0.20
K0	1.65±0.15
T	0.23±0.10

13” Reel



D2	330.0±5.0
D3	73Min.
D4	16.0±2.5
W1	18.0±3.0
Quantity: 5000PCS	